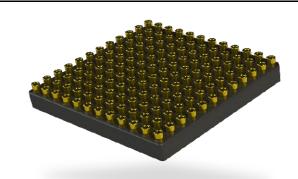
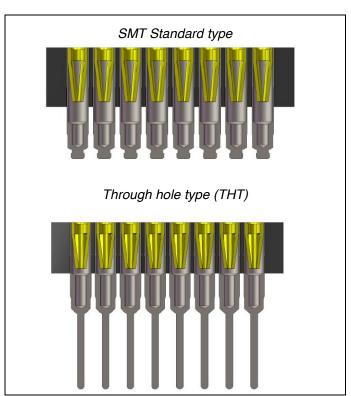
From 0.8 up to 1.27 mm pitch

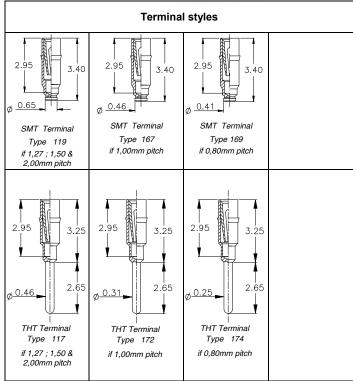


The E-tec Interconnect MiniGrid Socket is soldered to the target board and is designed to accept the BGA Solder Adapter (where the chip is soldered to the adapter board). As an alternative, this MiniGrid Socket is also designed to accept Test Sockets.

E-tec offers any pin-out, configuration and grid size. Special terminal designs are possible on request.







Specifications				
Terminal Type	Material	Plating	Socket	Others
117, 119, 167, 169, 172, 174	Terminal : CuZn	Sn over Ni over Cu	Material: Polyepoxy or other high temp mat.	Operating Temperature : −55°C to +125°C
	Contact clip : BeCu	Au over Ni over Cu		Processing Temperature : 260°C for 60 sec.

How to order

